

Title (en)  
METALLURGICAL IMPACT PAD

Title (de)  
METALLURGISCHER AUFPRALLBLOCK

Title (fr)  
PLAQUE D'AMORTISSEMENT MÉTALLURGIQUE

Publication  
**EP 2205769 A4 20110316 (EN)**

Application  
**EP 08837773 A 20081003**

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Abstract (en)  
[origin: EP2047928A1] An impact pad 20, formed from a refractory material capable of withstanding contact with molten metal, comprises a base 12 serving in use as an impact surface for molten metal, and a sidewall 14 extending generally upwardly therefrom. The sidewall 14 terminates at an upper surface 16 which is above the base 12 in use such that the base 12 and sidewall 14 define a receptacle for receiving molten metal. The sidewall 14 contains therein at least one channel 22, the at least one channel 22 having first and second ends 24, 26; the first end 24 being relatively closer to the base 12 at its intersection with the sidewall 14 than the second end 26. The at least one channel 22 being open ended at the second end 26 or tapering such that the at least one channel 22 has zero depth at its second end 26. The invention also relates to a tundish including an impact pad 20 as described above.

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**B22D 41/003** (2013.01 - EP); **B22D 41/02** (2013.01 - KR); **C21B 3/00** (2013.01 - KR); **C21B 7/14** (2013.01 - KR)

Citation (search report)  
• [Y] US 2004135298 A1 20040715 - XU DONG [CA], et al  
• [Y] US 5662823 A 19970902 - CLAAR BRIAN P [US], et al  
• [A] DE 2555286 A1 19770623 - KLOECKNER WERKE AG, et al  
• See references of WO 2009048810A1

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AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MT NL NO PL PT RO SE SI SK TR

DOCDB simple family (publication)  
**EP 2047928 A1 20090415**; AR 071250 A1 20100609; AU 2008311108 A1 20090416; AU 2008311108 B2 20120426; CA 2704622 A1 20090416; EP 2205769 A1 20100714; EP 2205769 A4 20110316; EP 2205769 B1 20131002; ES 2437594 T3 20140113; HR P20140001 T1 20140314; KR 101539793 B1 20150727; KR 20100088134 A 20100806; PL 2205769 T3 20140131; PT 2205769 E 20140103; SI 2205769 T1 20140131; TW 200927333 A 20090701; TW I450777 B 20140901; UA 100863 C2 20130211; WO 2009048810 A1 20090416; ZA 201003162 B 20110727

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